Pixel boards status

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## Introduction

The current design foresees the following boards (in its broadest sense):

Name	Function	Technology
HDI	Chip to endpiece. Power, data.	aluminium flex (LTU)
Interposer flex	HDI fan-out. Power, data.	4-layer flex (SwissPCB)
Endpiece flex	Concentrate 4 ladders. Power, data.	4-6-layer (SwissPCB)
Endring flex	Separate data from power. Possibly: filtering, repeater	4-6-layer (SwissPCB)

Layers 1/2: No endring flex, endpiece flex takes this role.



- > Final board layouts can't be designed before final chip
- Readout cable has an impact
- ▶ Will talk about boards for thermo-mechanical mock-up instead
- Interposer has been proven to work (see talk by Marco Zimmermann in April collaboration meeting)



Thermo-mechanical mock-up comes in two flavours:

- Tape heaters: lasered meanders on aluminium-polyimid laminate.
  Reasonably cheap, UHD in-house production, doesn't match final material
- Silicon heaters: heat meanders on silicon chips, tab-bonded to HDI Matches final materials, costly
- Target: build full central station with tape heaters and representative fraction with silicon heaters
- $\blacktriangleright$  Silicon heater option requires all boards  $\Rightarrow$  tests mechanical aspects
- Function: Heat with target power densities 250 mW/cm<sup>2</sup> and above. Readout of temperatures (4-wire resistance measurement per L3/4 tape heater or silicon heater)





L1 one half shell exists Works fine. More in the making.

Awaiting some mounting parts from workshop

Has stainless steel chips as placeholders



## Status – Tape-heater

- ► L1 ready, more to come
- ► L2 in preparation
- ▶ L3/4 in preparation. Tape heaters exist, see mechanical status session
- > "Boards" are all made of lasered aluminium, not much to learn for the detector



# Status – Si-heater

All types of flexes needed

- > Si heaters exist: 96 pcs. More to be ordered.
- ▶ L1/2
  - ► HDI Designed, ordered with LTU. Expected end of July.
  - Interposer flex Designed, under review.
  - Endpiece flex Design started, awaited in next weeks.
- ► L4
  - $\blacktriangleright$  HDI In design, review ongoing. To be ordered after first experience with L1/2 HDI
  - interposer flex Awaits redesign due to change in mechanics (shift of bend position, see mechanics)
  - Endpiece flex Design pending
  - Endring flex Design pending





Latest status of HDI design (this Mon)

Shows left end, towards interposer.





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### Board issues

- Catching up. Contract issues delayed order of HDI and Si heaters (latter still uncertain, but about 90 available now)
- Electrical issues. Readout cable has high impact (connector, impedance, need for repeater)
- Quality control: will be defined for final parts but mechanical lessons will be learned in mock-up.



# Boards plans

- > Fabricate tape heater parts this summer. Needed for thermal studies.
- Ramp-up fabrication of Si-heater at PSU/UHD: Establish procedure for SpTA-bonding. Late summer.
- ► Finalise designs of all Si-heater boards. Next weeks.
- ► Test mechanical shape of all boards. Late summer, autumn.
- Operational tests. Autumn.

Goal: end of year all electrical aspects known we can learn from this mock-up



## Mechanical



An improved version of the endring jig (Simon Muley)

One facet always horizontal. By tilting and turning the "shoe" all four ladders can be chosen.



### Mechanical



Endring mounts ordered

Will need an adapter to insert it into our test stand.



## Mech plans

- ▶ Fabricate more L1 half-shells, prove feasibility of tooling.
- Transfer this to L2
- ▶ Fabricate one (two) L1/2 cylinders for thermal testing
- Move on with Si heaters

Goal: Have a full vertex detector mock-up in Si heater operational by autumn



# ENCORE

